◆CARRIER TAPE DIMENSIONS
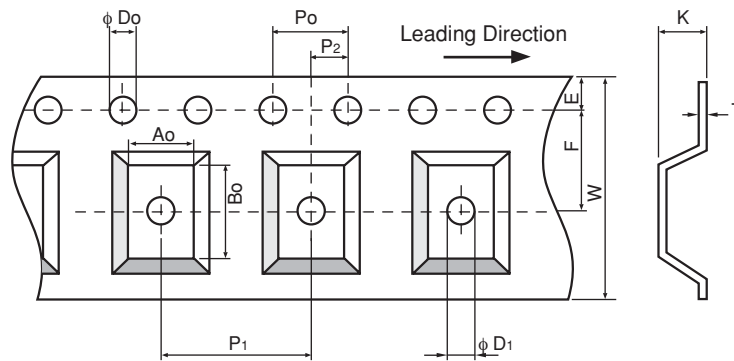
Chip size	Taping code	Dimensions [mm]											
		A_0 ±0.1	B_0 ±0.1	W ±0.3	F ±0.05	E ±0.1	P_1 ±0.1	P_2 ±0.04	P_0 ±0.1	ϕD_0 ±0.1	ϕD_1 +0.2/-0	K ±0.1	T ±0.05
3216	A 1	2.00	3.60	8.0	3.5	1.75	4.0	2.0	4.0	1.5	1.0	1.4	0.20
	A 2											1.8	0.25
3225	B 1	2.90	3.60	8.0	3.5	1.75	4.0	2.0	4.0	1.5	1.0	1.8	0.25
	B 2											2.2	0.25
	B 3											2.4	0.25
4532	C 1	3.60	4.90	12.0	5.5	1.75	8.0	2.0	4.0	1.5	1.5	1.8	0.25
	C 2											2.2	0.25
	C 3											2.4	0.25
	C 4											3.0	0.25
5750	D 1	5.40	6.10	12.0	5.5	1.75	8.0	2.0	4.0	1.5	1.5	2.2	0.25
	D 2											2.6	0.25
	D 3											3.0	0.25

◆REEL DIMENSIONS
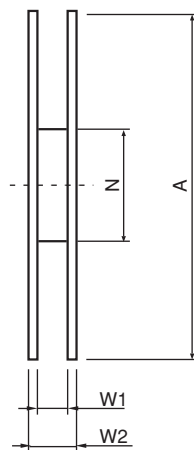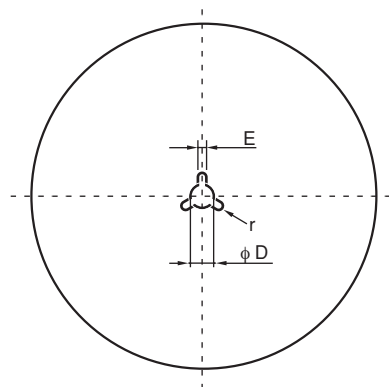
Chip size	Reel size	Quantity
3216	φ180mm	2000pcs/real
3225	φ180mm	2000pcs/real
4532	φ254mm	1500pcs/real
5750	φ254mm	1500pcs/real

（mm）

Taping code	A	N	W 1	W 2	D	E	r
A, B	φ180±1.0	φ60±1.0	9.5±1.0	13.1±1.0	φ13.0±0.2	2.0±0.5	1.0±0.2
C, D	φ254±1.0	φ100±1.0	13.5±1.0	18.5±1.0	φ13.0±0.2	2.0±0.5	1.0±0.2

## ● SOLDERING CONDITIONS

◆ REFLOW SOLDERING CONDITIONS

1) Surface temperature of capacitor shall not exceed the value shown in the following table.

2) Period that temperature at surface of capacitor becomes more than 200°C and peak temperature shall not exceed t2 and t3 seconds shown in the following table, respectively.

3) Holding time at the peak temperature shall be as short as possible.

4) Preheat temperature shall be made between 150 to 180°C and made maximum t1 seconds shown in the following table.

5) Soldering frequency shall be less than 2 times. The second soldering should be carried after the capacitor itself has returned to normal temperature.
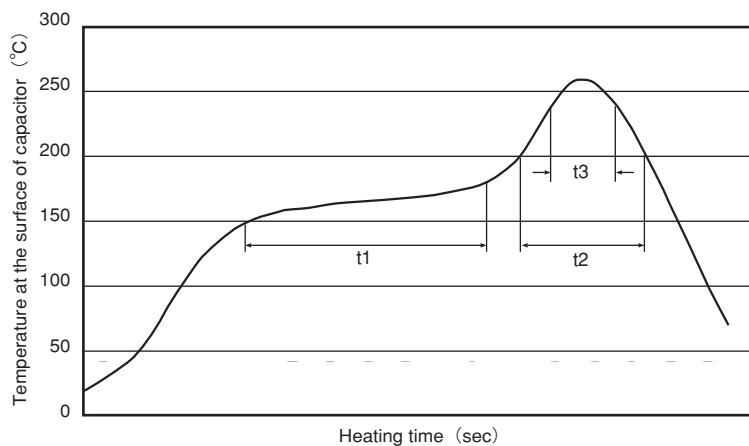
	(T)	(t1)	(t2)	(t3)
150~180°C	260°C	180sec	90sec	40sec

◆ RECOMMENDED LAND SIZE

For designing land size, refer to the following recommended land size.
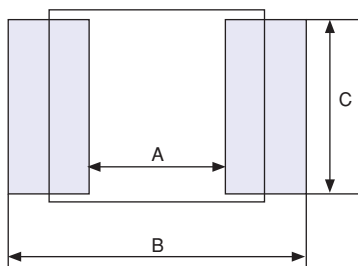
Chip size	Dimensions (mm)		
	A	B	C
3216	1.8	3.6	1.4
3225	1.8	3.6	2.3
4532	2.7	5.7	3.0
5750	3.5	7.8	4.5